

ABSTRACT

The epoxy resin curing agent of the present invention comprises a polyamino compound obtainable by addition reaction of aliphatic diamine represented by the formula (1) and styrene and a curing accelerator comprising an organic compound having at least one carboxyl group and at least one hydroxyl group within the molecule, which can achieve a low viscosity without containing environmental harmful substances such as phenol and solvents. In addition, the epoxy resin composition using said epoxy resin curing agent shows an excellent curability at low temperature and it provides a cured coating film having excellent appearance.



wherein A is a phenylene group or a cyclohexylene group